



MMBT3906

PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- **Epitaxial Planar Die Construction**
- Complementary NPN Type Available (MMBT3904)
- Ideal for Low Power Amplification and Switching
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

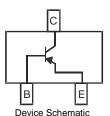
Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic, "Green" Molding Compound, (Note 3). UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.008 grams (approximate)





Top View



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-40	V
Collector-Emitter Voltage	V _{CEO}	-40	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current - Continuous (Note 1)	I _C	-200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P_{D}	300	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ hetaJA}$	417	°C/W
Operating and Storage and Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- No purposefully added lead.
- 3. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.



Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-40	_	V	$I_C = -10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 4)	$V_{(BR)CEO}$	-40	_	V	$I_C = -1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-5.0		V	$I_E = -10\mu A, I_C = 0$	
Collector Cutoff Current	I _{CEX}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
Collector Cutoff Current	I _{CBO}		-50	nA	$V_{CB} = -30V, I_E = 0$	
Base Cutoff Current	I_{BL}		-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h _{FE}	60 80 100 60 30	 300 	-	$\begin{split} I_C &= -100 \mu A, \ V_{CE} = -1.0 V \\ I_C &= -1.0 m A, \ V_{CE} = -1.0 V \\ I_C &= -10 m A, \ V_{CE} = -1.0 V \\ I_C &= -50 m A, \ V_{CE} = -1.0 V \\ I_C &= -100 m A, \ V_{CE} = -1.0 V \end{split}$	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	-0.25 -0.40	٧	$I_C = -10\text{mA}, I_B = -1.0\text{mA}$ $I_C = -50\text{mA}, I_B = -5.0\text{mA}$	
Base-Emitter Saturation Voltage		-0.65 —	-0.85 -0.95	V	$I_C = -10\text{mA}, I_B = -1.0\text{mA}$ $I_C = -50\text{mA}, I_B = -5.0\text{mA}$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}		4.5	pF	$V_{CB} = -5.0V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance	C _{ibo}		10	pF	$V_{EB} = -0.5V$, $f = 1.0MHz$, $I_C = 0$	
Input Impedance	h _{ie}	2.0	12	kΩ		
Voltage Feedback Ratio	h _{re}	0.1	10	x 10 ⁻⁴	$V_{CE} = 10V, I_{C} = 1.0mA,$	
Small Signal Current Gain	h _{fe}	100	400		f = 1.0kHz	
Output Admittance	h _{oe}	3.0	60	μS		
Current Gain-Bandwidth Product	f _T	250		MHz	$V_{CE} = -20V, I_{C} = -10mA,$ f = 100MHz	
Noise Figure	NF		4.0	dB	V_{CE} = -5.0V, I_{C} = -100 μ A, R_{S} = 1.0k Ω , f = 1.0kHz	
SWITCHING CHARACTERISTICS	· · · · · · · · · · · · · · · · · · ·					
Delay Time	t _d	_	35	ns	$V_{CC} = -3.0V, I_{C} = -10mA,$	
Rise Time	t _r		35	ns	$V_{BE(off)} = 0.5V, I_{B1} = -1.0mA$	
Storage Time	ts		225	ns	V _{CC} = -3.0V, I _C = -10mA,	
Fall Time	t _f	_	75	ns	$I_{B1} = I_{B2} = -1.0 \text{mA}$	

Notes: 4. Short duration pulse test used to minimize self-heating effect.

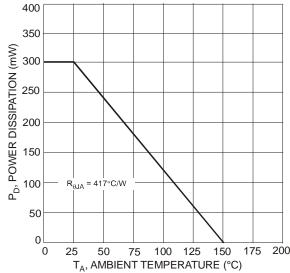
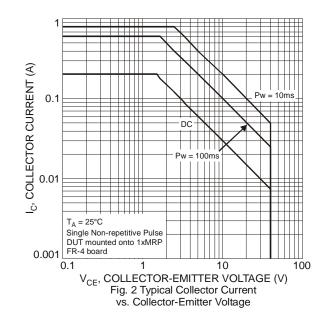
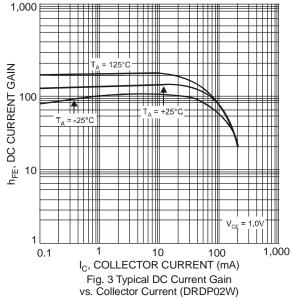
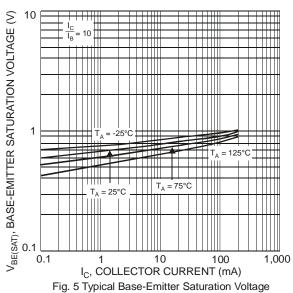


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 1)









vs. Collector Current

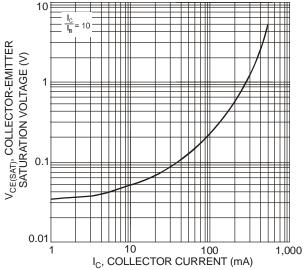
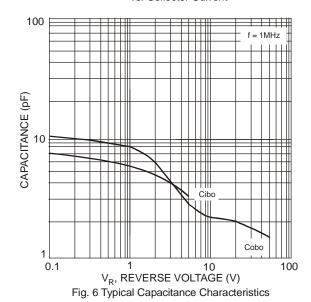


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

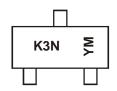


Ordering Information (Note 5)

ſ	Part Number	Case	Packaging
	MMBT3906 -7-F	SOT-23	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



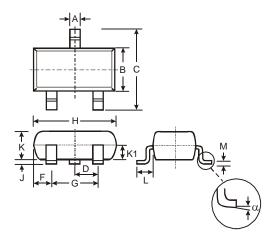
K3N = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	J	K	L	M	Ν	Р	R	S	Т	J	>	W	Χ	Υ	Z	Α	В	С
Month	Jan	1	Feb	Mai	r	Apr	May	/	Jun	Jul		Aug	Sep		Oct	Nov	,	Dec
Code	1		2	3		4	5		6	7		8	9		0	N		D

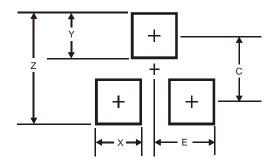


Package Outline Dimensions



SOT-23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All	All Dimensions in mm						

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Υ	0.9
С	2.0
E	1.35

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